

Title (en)

METHOD AND SYSTEM FOR EMBEDDED TEMPERATURE AND/OR STRAIN SENSORS

Title (de)

VERFAHREN UND SYSTEM FÜR EINGEBETTETE TEMPERATUR- UND/ODER DEHNUNGSSSENSOREN

Title (fr)

PROCÉDÉ ET SYSTÈME DESTINÉS À DES CAPTEURS DE TEMPÉRATURE ET/OU DE CONTRAINTE INCORPORÉS

Publication

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Application

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Abstract (en)

[origin: US2012293646A1] A system and method for monitoring system including a embedded sensor coupled to an article, wherein the embedded sensor is a direct write embedded sensor using a high temperature light emitting material. A camera system detects illumination signals from the embedded sensors. A processing section processes the illumination signals and determines gas/surface temperatures and strain data for the article.

IPC 8 full level

H04N 5/30 (2006.01); **B23P 15/00** (2006.01); **B23P 17/00** (2006.01); **H04N 7/18** (2006.01)

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